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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv08km101-e-so

TABLE 1-4: DEVICE FEATURES FOR THE PIC24FV16KM104 FAMILY

Features	PIC24FV16KM104	PIC24FV16KM102	PIC24FV08KM102	PIC24FV08KM101
Operating Frequency	DC-32 MHz			
Program Memory (bytes)	16K	16K	8K	8K
Program Memory (instructions)	5632	5632	2816	2816
Data Memory (bytes)	1024			
Data EEPROM Memory (bytes)	512			
Interrupt Sources (soft vectors/NMI traps)	25 (21/4)			
Voltage Range	2.0-5.5V			
I/O Ports	PORTA<11:7,5:0> PORTB<15:0> PORTC<9:0>	PORTA<7,5:0> PORTB<15:0>		PORTA<5:0> PORTB<15:12,9:7,4,2:0>
Total I/O Pins	37	23		17
Timers	5 (One 16-bit timer, two MCCPs/SCCPs with up to two 16/32 timers each)			
Capture/Compare/PWM modules MCCP SCCP	 1 1			
Serial Communications MSSP UART	 1 1			
Input Change Notification Interrupt	36	22		16
12-Bit Analog-to-Digital Module (input channels)	22	19		16
Analog Comparators	1			
8-Bit Digital-to-Analog Converters	—			
Operational Amplifiers	—			
Charge Time Measurement Unit (CTMU)	Yes			
Real-Time Clock and Calendar (RTCC)	—			
Configurable Logic Cell (CLC)	1			
Resets (and delays)	POR, BOR, RESET Instruction, $\overline{\text{MCLR}}$, WDT, Illegal Opcode, REPEAT Instruction, Hardware Traps, Configuration Word Mismatch (PWRT, OST, PLL Lock)			
Instruction Set	76 Base Instructions, Multiple Addressing Mode Variations			
Packages	44-Pin QFN/TQFP, 48-Pin UQFN	28-Pin SPDIP/SSOP/SOIC/QFN		20-Pin SOIC/SSOP/PDIP

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

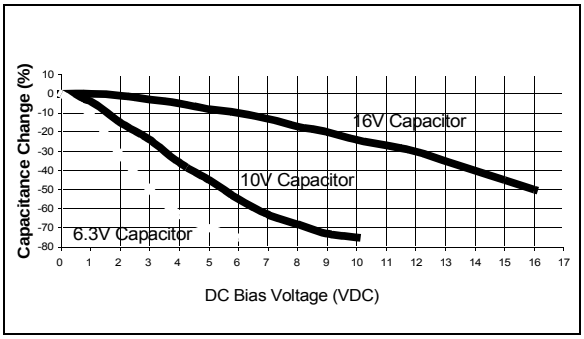
Typical low-cost, 10 µF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R), or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 µF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

A typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating, so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at 16V for the 3.3V or 2.5V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pins, Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

For device emulation, ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 26.0 "Development Support"**.

3.3.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

1. 32-bit signed/16-bit signed divide
2. 32-bit unsigned/16-bit unsigned divide
3. 16-bit signed/16-bit signed divide
4. 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. Sixteen-bit signed and unsigned DIV instructions can specify any W register for both the 16-bit divisor (Wn), and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.3.3 MULTI-BIT SHIFT SUPPORT

The PIC24F ALU supports both single bit and single-cycle, multi-bit arithmetic and logic shifts. Multi-bit shifts are implemented using a shifter block, capable of performing up to a 15-bit arithmetic right shift, or up to a 15-bit left shift, in a single cycle. All multi-bit shift instructions only support Register Direct Addressing for both the operand source and result destination.

A full summary of instructions that use the shift operation is provided in Table 3-2.

TABLE 3-2: INSTRUCTIONS THAT USE THE SINGLE AND MULTI-BIT SHIFT OPERATION

Instruction	Description
ASR	Arithmetic shift right source register by one or more bits.
SL	Shift left source register by one or more bits.
LSR	Logical shift right source register by one or more bits.

TABLE 4-21: PORTA REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11(4,5)	Bit 10(4,5)	Bit 9(4,5)	Bit 8(4,5)	Bit 7(4)	Bit 6(3)	Bit 5(2)	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	2C0h	—	—	—	—	TRISA11	TRISA10	TRISA9	TRISA8	TRISA7	TRISA6	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	0FDF(1)
PORTA	2C2h	—	—	—	—	RA11	RA10	RA9	RA8	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	xxxx
LATA	2C4h	—	—	—	—	LATA11	LATA10	LATA9	LATA8	LATA7	LATA6	—	LATA4	LATA3	LATA2	LATA1	LATA0	xxxx
ODCA	2C6h	—	—	—	—	ODA11	ODA10	ODA9	ODA8	ODA7	ODA6	—	ODA4	ODA3	ODA2	ODA1	ODA0	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: Reset value depends on the device type; the PIC24F16KM204 value is shown.
2: These bits are only available when MCLRE (FPOR<7>) = 0.
3: These bits are not implemented in FV devices.
4: These bits are not implemented in 20-pin devices.
5: These bits are not implemented in 28-pin devices.

TABLE 4-22: PORTB REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11(2)	Bit 10(2)	Bit 9	Bit 8	Bit 7	Bit 6(2)	Bit 5(2)	Bit 4	Bit 3(2)	Bit 2	Bit 1	Bit 0	All Resets
TRISB	2C8h	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF(1)
PORTB	2CAh	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	2CCh	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	2CEh	ODB15	ODB14	ODB13	ODB12	ODB11	ODB10	ODB9	ODB8	ODB7	ODB6	ODB5	ODB4	ODB3	ODB2	ODB1	ODB0	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: Reset value depends on the device type; the PIC24F16KM204 value is shown.
2: These bits are not implemented in 20-pin devices.

TABLE 4-23: PORTC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9(2,3)	Bit 8(2,3)	Bit 7(2,3)	Bit 6(2,3)	Bit 5(2,3)	Bit 4(2,3)	Bit 3(2,3)	Bit 2(2,3)	Bit 1(2,3)	Bit 0(2,3)	All Resets
TRISC	2D0h	—	—	—	—	—	—	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	03FF(1)
PORTC	2D2h	—	—	—	—	—	—	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATTC	2D4h	—	—	—	—	—	—	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	2D6h	—	—	—	—	—	—	ODC9	ODC8	ODC7	ODC6	ODC5	ODC4	ODC3	ODC2	ODC1	ODC0	0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition, r = reserved.
Note 1: Reset value depends on the device type; the PIC24F16KM204 value is shown.
2: These bits are not implemented in 20-pin devices.
3: These bits are not implemented in 28-pin devices.

NOTES:

13.3 Output Compare Mode

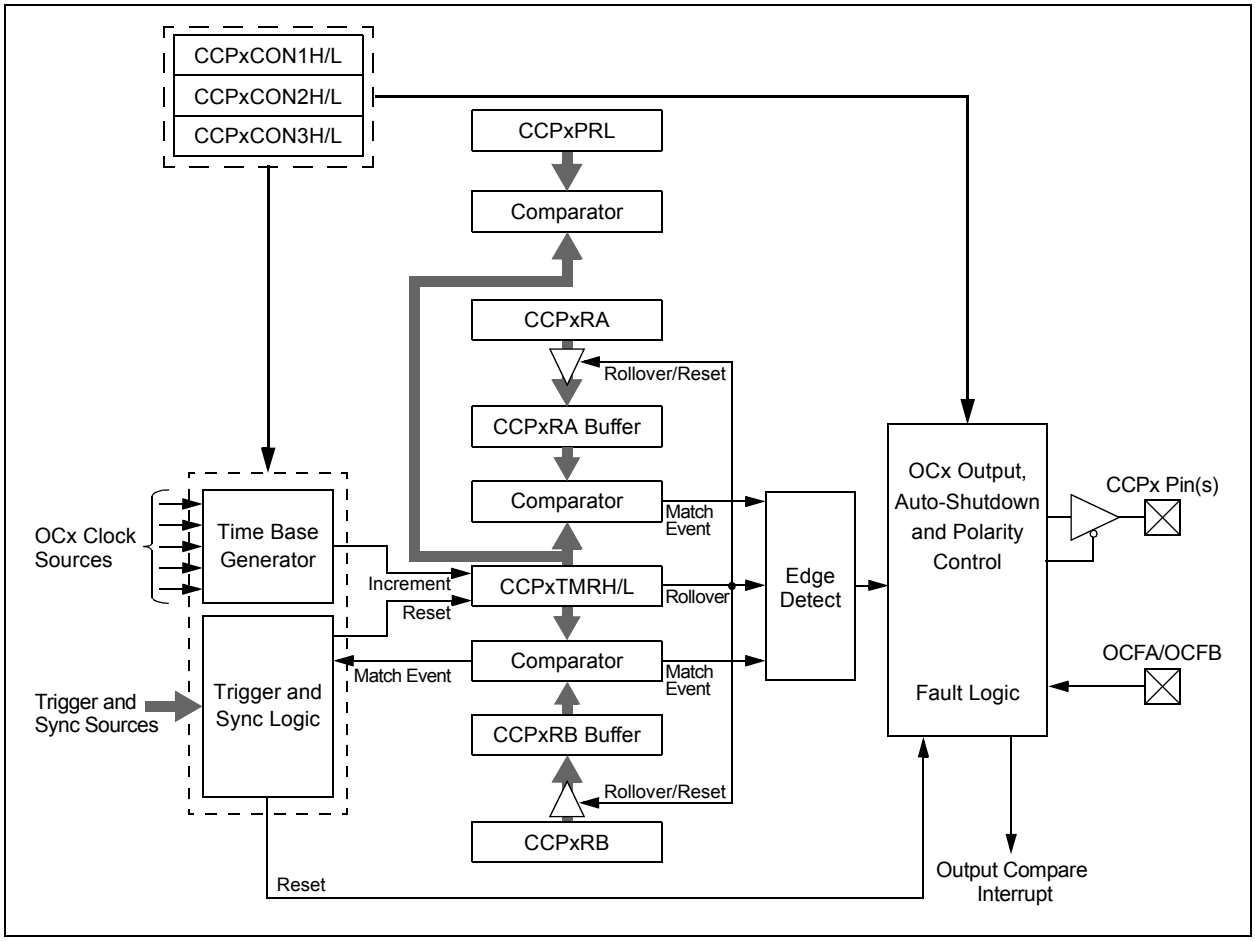
Output Compare mode compares the Timer register value with the value of one or two Compare registers, depending on its mode of operation. The Output Compare x module on compare match events has the ability to generate a single output transition or a train of output pulses. Like most PIC® MCU peripherals, the Output Compare x module can also generate interrupts on a compare match event.

Table 13-3 shows the various modes available in Output Compare modes.

TABLE 13-3: OUTPUT COMPARE/PWM MODES

MOD<3:0> (CCPxCON1L<3:0>)	T32 (CCPxCON1L<5>)	Operating Mode	
0001	0	Output High on Compare (16-bit)	Single Edge Mode
0001	1	Output High on Compare (32-bit)	
0010	0	Output Low on Compare (16-bit)	
0010	1	Output Low on Compare (32-bit)	
0011	0	Output Toggle on Compare (16-bit)	
0011	1	Output Toggle on Compare (32-bit)	
0100	0	Dual Edge Compare (16-bit)	Dual Edge Mode
0101	0	Dual Edge Compare (16-bit buffered)	PWM Mode
0110	0	Center-Aligned Pulse (16-bit buffered)	Center PWM
0111	0	Variable Frequency Pulse (16-bit)	
0111	1	Variable Frequency Pulse (32-bit)	

FIGURE 13-5: OUTPUT COMPARE x BLOCK DIAGRAM



REGISTER 14-5: SSPxCON2: MSSPx CONTROL REGISTER 2 (I^2C™ MODE)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GCEN	ACKSTAT	ACKDT(1)	ACKEN(2)	RCEN(2)	PEN(2)	RSEN(2)	SEN(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **GCEN:** General Call Enable bit (Slave mode only)
1 = Enables interrupt when a general call address (0000h) is received in the SSPxSR
0 = General call address is disabled

bit 6 **ACKSTAT:** Acknowledge Status bit (Master Transmit mode only)
1 = Acknowledge was not received from slave
0 = Acknowledge was received from slave

bit 5 **ACKDT:** Acknowledge Data bit (Master Receive mode only)(1)
1 = No Acknowledge
0 = Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit (Master mode only)(2)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins and transmits ACKDT data bit; automatically cleared by hardware
0 = Acknowledge sequence is Idle

bit 3 **RCEN:** Receive Enable bit (Master Receive mode only)(2)
1 = Enables Receive mode for I^2C
0 = Receive is Idle

bit 2 **PEN:** Stop Condition Enable bit (Master mode only)(2)
1 = Initiates Stop condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Stop condition is Idle

bit 1 **RSEN:** Repeated Start Condition Enable bit (Master mode only)(2)
1 = Initiates Repeated Start condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Repeated Start condition is Idle

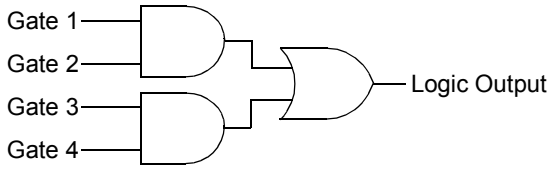
bit 0 **SEN:** Start Condition Enable bit(2)
Master Mode:
1 = Initiates Start condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Start condition is Idle
Slave Mode:
1 = Clock stretching is enabled for both slave transmit and slave receive (stretch is enabled)
0 = Clock stretching is disabled

Note 1: The value that will be transmitted when the user initiates an Acknowledge sequence at the end of a receive.

2: If the I^2C module is active, these bits may not be set (no spooling) and the SSPxBUF may not be written (or writes to the SSPxBUF are disabled).

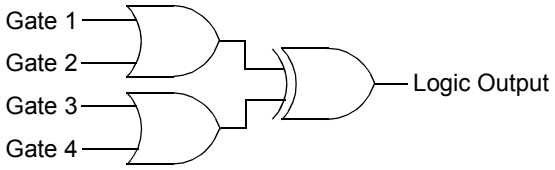
FIGURE 17-2: CLCx LOGIC FUNCTION COMBINATORIAL OPTIONS

AND – OR



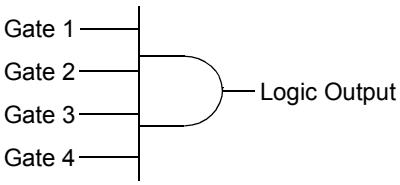
MODE<2:0> = 000

OR – XOR



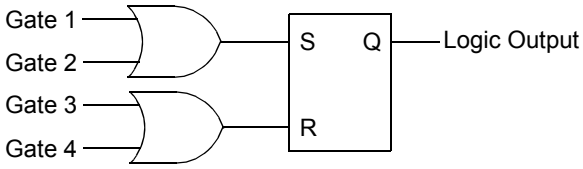
MODE<2:0> = 001

4-Input AND



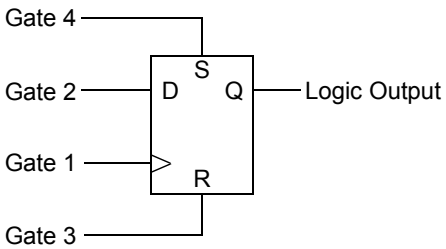
MODE<2:0> = 010

S-R Latch



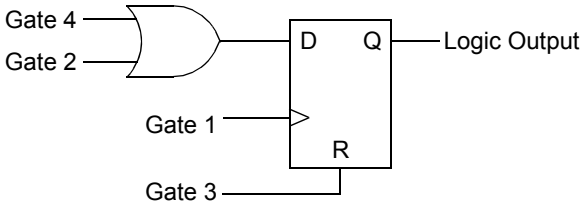
MODE<2:0> = 011

1-Input D Flip-Flop with S and R



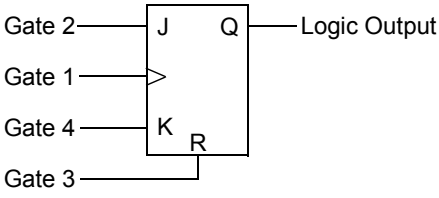
MODE<2:0> = 100

2-Input D Flip-Flop with R



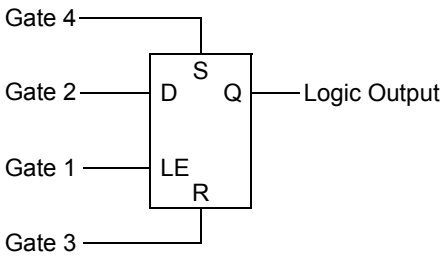
MODE<2:0> = 101

J-K Flip-Flop with R



MODE<2:0> = 110

1-Input Transparent Latch with S and R



MODE<2:0> = 111

To perform an A/D conversion:

1. Configure the A/D module:
   a) Configure the port pins as analog inputs and/or select band gap reference inputs (ANSx registers).
   b) Select the voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:4> and AD1CON3<12:8>).
   e) Configure the MODE12 bit to select A/D resolution (AD1CON1<10>).
   f) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
   g) Select the interrupt rate (AD1CON2<6:2>).
   h) Turn on the A/D module (AD1CON1<15>).
2. Configure the A/D interrupt (if required):
   a) Clear the AD1IF bit.
   b) Select the A/D interrupt priority.

To perform an A/D sample and conversion using Threshold Detect scanning:

1. Configure the A/D module:
   a) Configure the port pins as analog inputs (ANSx registers).
   b) Select the voltage reference source to match the expected range on the analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:4> and AD1CON3<12:8>).
   e) Configure the MODE12 bit to select A/D resolution (AD1CON1<10>).
   f) Select how the conversion results are presented in the buffer (AD1CON1<9:8>).
   g) Select the interrupt rate (AD1CON2<6:2>).
2. Configure the threshold compare channels:
   a) Enable auto-scan; set the ASEN bit (AD1CON5<15>).
   b) Select the Compare mode, “Greater Than, Less Than or Windowed”; set the CMx bits (AD1CON5<1:0>).
   c) Select the threshold compare channels to be scanned (AD1CSSH, AD1CSSL).
   d) If the CTMU is required as a current source for a threshold compare channel, enable the corresponding CTMU channel (AD1CTMENH, AD1CTMENL).
   e) Write the threshold values into the corresponding ADC1BUFx registers.
   f) Turn on the A/D module (AD1CON1<15>).

Note: If performing an A/D sample and conversion, using Threshold Detect in Sleep Mode, the RC A/D clock source must be selected before entering into Sleep mode.

3. Configure the A/D interrupt (OPTIONAL):
   a) Clear the AD1IF bit.
   b) Select the A/D interrupt priority.

REGISTER 19-1: AD1CON1: A/DA/D CONTROL REGISTER 1 (CONTINUED)

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** A/D Sample Auto-Start bit
1 = Sampling begins immediately after the last conversion; SAMP bit is auto-set
0 = Sampling begins when the SAMP bit is manually set

bit 1 **SAMP:** A/D Sample Enable bit
1 = A/D Sample-and-Hold amplifiers are sampling
0 = A/D Sample-and-Hold amplifiers are holding

bit 0 **DONE:** A/D Conversion Status bit
1 = A/D conversion cycle has completed
0 = A/D conversion cycle has not started or is in progress

Note 1: This version of the TMR1 Trigger allows A/D conversions to be triggered from TMR1 while the device is operating in Sleep mode. The SSRC<3:0> = 0101 option allows conversions to be triggered in Run or Idle modes only.

REGISTER 19-8: AD1CSSH: A/D INPUT SCAN SELECT REGISTER (HIGH WORD)(1)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
—	CSS30	CSS29	CSS28	CSS27	CSS26	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS23	CSS22	CSS21	CSS20(2)	CSS19(2)	CSS18	CSS17	CSS16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-10 **CSS<30:26>:** A/D Input Scan Selection bits
1 = Includes the corresponding channel for input scan
0 = Skips the channel for input scan

bit 9-8 **Unimplemented:** Read as '0'

bit 7-0 **CSS<23:16>:** A/D Input Scan Selection bits(2)
1 = Includes the corresponding channel for input scan
0 = Skips the channel for input scan

Note 1: Unimplemented channels are read as '0'. Do not select unimplemented channels for sampling as indeterminate results may be produced.
2: The CSS<20:19> bits are not implemented in 20-pin devices.

REGISTER 19-9: AD1CSSL: A/D INPUT SCAN SELECT REGISTER (LOW WORD)(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS15	CSS14	CSS13	CSS12	CSS11	CSS10	CSS9	CSS8(2,3)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS7(2,3)	CSS6(2,3)	CSS5(2)	CSS4	CSS3	CSS2	CSS1	CSS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **CSS<15:0>:** A/D Input Scan Selection bits(2,3)
1 = Includes the corresponding ANx input for scan
0 = Skips the channel for input scan

Note 1: Unimplemented channels are read as '0'. Do not select unimplemented channels for sampling as indeterminate results may be produced.
2: The CSS<8:5> bits are not implemented in 20-pin devices.
3: The CSS<8:6> bits are not implemented in 28-pin devices.

REGISTER 24-1: CTMUCON1L: CTMU CONTROL 1 LOW REGISTER (CONTINUED)

bit 1-0 **IRNG<1:0>:** Current Source Range Select bits
11 = 100 × Base Current
10 = 10 × Base Current
01 = Base Current Level (0.55 µA nominal)
00 = 1000 × Base Current

26.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16 and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

26.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

26.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

26.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

26.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

26.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

26.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

26.9 PICkit 3 In-Circuit Debugger/ Programmer

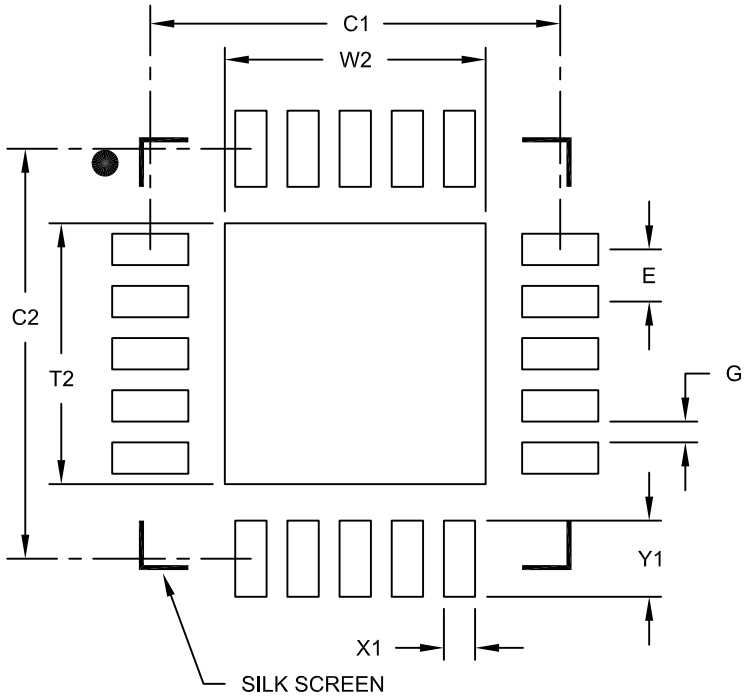
The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

26.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

20-Lead Plastic Quad Flat, No Lead Package (ML) - 4x4 mm Body [QFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			2.50
Optional Center Pad Length	T2			2.50
Contact Pad Spacing	C1		3.93	
Contact Pad Spacing	C2		3.93	
Contact Pad Width	X1			0.30
Contact Pad Length	Y1			0.73
Distance Between Pads	G	0.20		

Notes:

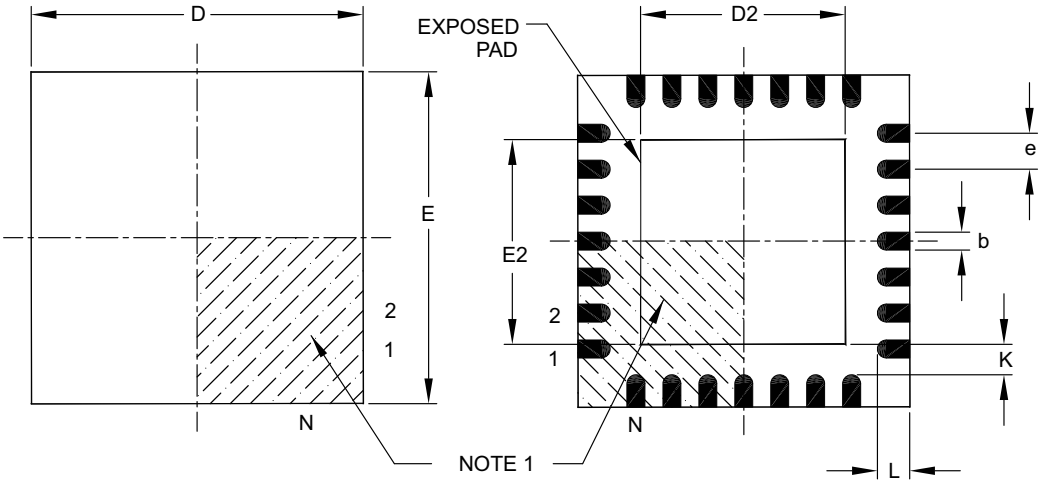
1. Dimensioning and tolerancing per ASME Y14.5M

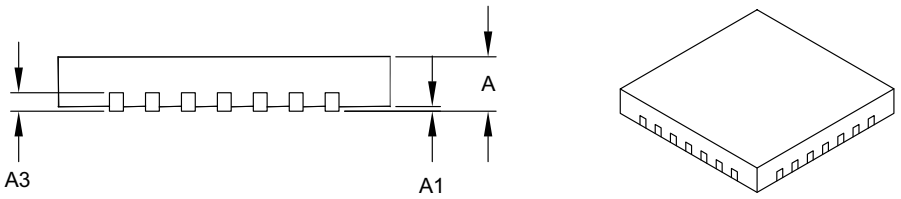
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2126A

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

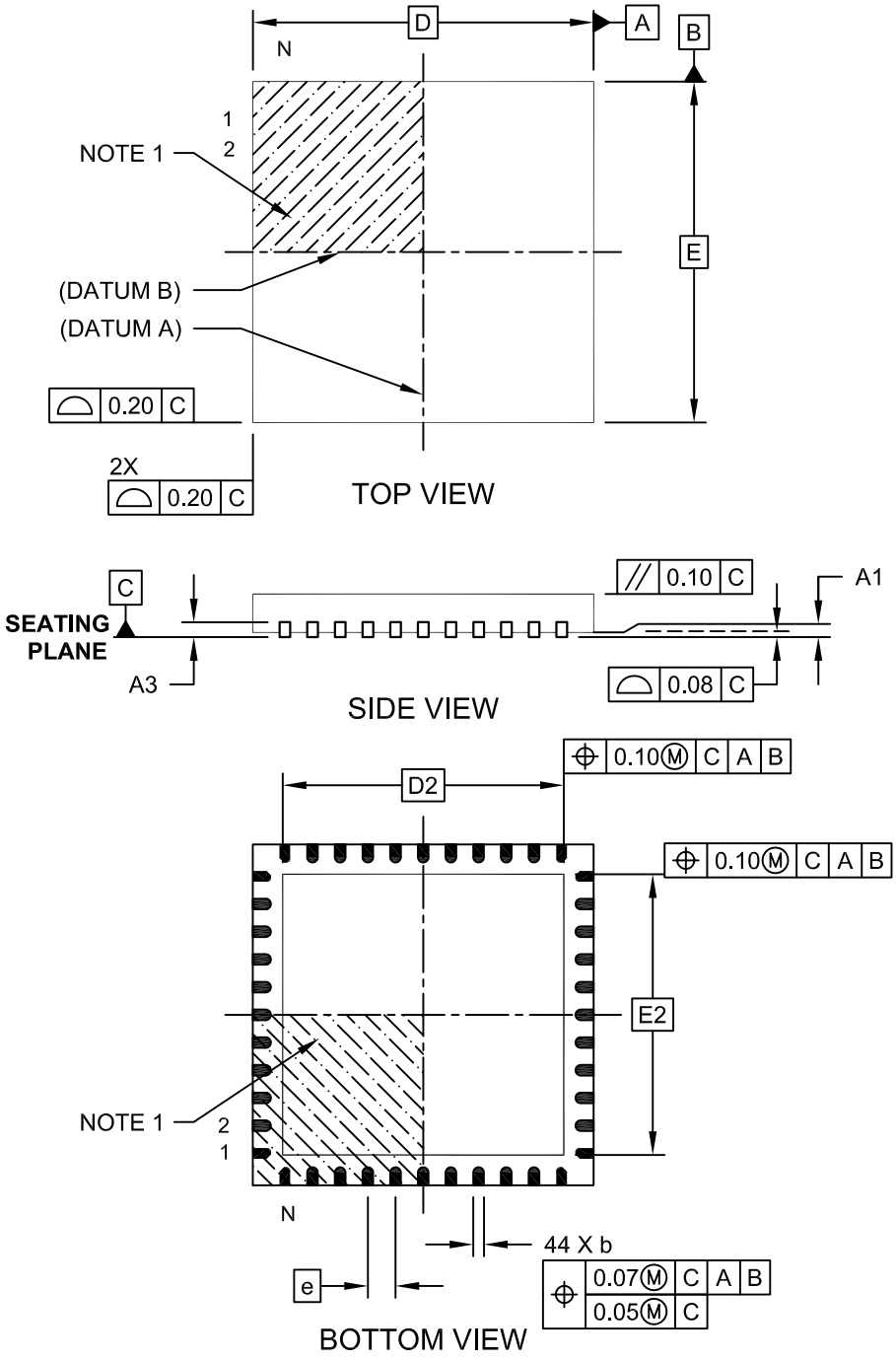
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

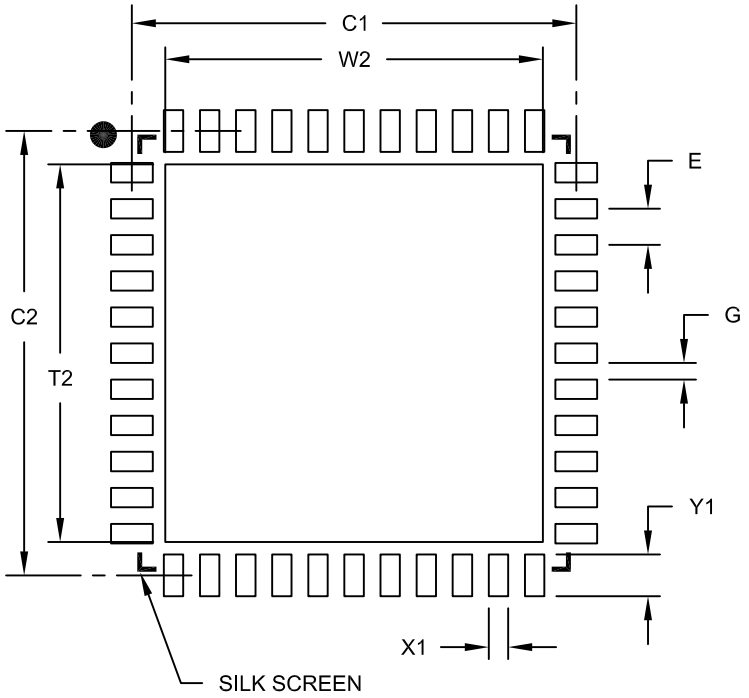
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103C Sheet 1 of 2

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

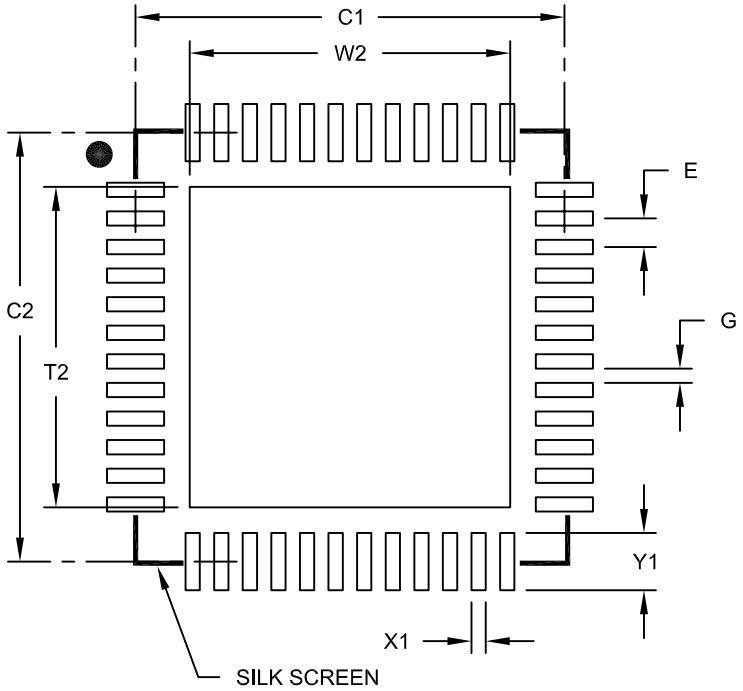
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A